

# LNPT™ COLORCOMP™ COMPOUND 9X02692H

## DESCRIPTION

COLORCOMP 9X02695H compound is based on Polyphenylsulfone (PPSU). Added features of this grade include High Heat Resistance, Easy Processing and Healthcare.

GENERAL INFORMATION	
Features	High Flow, Healthcare/Formula lock, High temperature resistance, No PFAS intentionally added
Fillers	Unreinforced
Polymer Types	Polyphenylsulfone (PPSU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Water Management
Consumer	Home Appliances
Hygiene and Healthcare	Pharmaceutical Packaging and Drug Delivery, Surgical devices, General Healthcare, Patient Testing
Packaging	Industrial Packaging, Food & Beverage

## TYPICAL PROPERTY VALUES

Revision 20240408

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL <sup>(1)</sup></b>			
Tensile Modulus, 50 mm/min	2340	MPa	ASTM D638
Tensile Stress, yld, Type I, 50 mm/min	69.6	MPa	ASTM D638
Tensile Strain, yld, Type I, 50 mm/min	7.2	%	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	90	%	ASTM D638
Flexural Modulus, 1.3 mm/min, 50 mm span	2410	MPa	ASTM D790
Flexural Stress at 5% strain, 1.3 mm/min, 50 mm span	91	MPa	ASTM D790
<b>IMPACT <sup>(1)</sup></b>			
Izod Impact, notched, 23°C	690	J/m	ASTM D256
<b>THERMAL <sup>(1)</sup></b>			
HDT, 1.82 MPa, 3.2mm, unannealed	207	°C	ASTM D648
CTE, -30°C to 30°C, flow	5.5E-05	1/°C	ASTM D696
<b>PHYSICAL <sup>(1)</sup></b>			
Specific Gravity	1.3	-	ASTM D792
Water Absorption, (23°C/24hrs)	0.37	%	ASTM D570
Water Absorption, (23°C/Saturated)	1.1	%	ASTM D570
Melt Flow Rate, 365°C/5.0 kgf	17	g/10 min	ASTM D1238
Mold Shrinkage, flow <sup>(2)</sup>	0.7	%	SABIC method
<b>FLAME CHARACTERISTICS</b>			
UL Recognized, 94V-0 Flame Class Rating <sup>(3)</sup>	≥0.75	mm	UL 94
<b>FLAMMABILITY PROPERTIES</b>			
UL Yellow Card Link <sup>(3)</sup>	UL Certification: E121562 - Component - Plastics		

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>INJECTION MOLDING <sup>(4)</sup></b>			
Drying Temperature	150	°C	
Drying Time	2.5	Hrs	
Maximum Moisture Content	.05	%	
Melt Temperature	360 – 390	°C	
Mold Temperature	140 – 160	°C	
Back Pressure	0.3 – 0.7	MPa	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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